

10/026,239**Patent
IBM Docket No. FIS920010261US1****CLAIMS APPENDIX**

1. A process for cleaning paste residue from a workpiece comprising the steps of obtaining a workpiece having a paste residue thereon and electrolytically contacting the workpiece with an aqueous solution containing 0.2 to 2 weight percent TMAH.
2. The process of claim 1 wherein the step of electrolytically contacting comprises spraying the workpiece with the aqueous solution.
3. The process of claim 1 wherein the step of electrolytically contacting comprises immersing the workpiece in the aqueous solution.
4. The process of claim 1 wherein the aqueous solution in the step of electrolytically contacting is maintained at a temperature of 25 to 80 °C.
5. The process of claim 1 wherein the aqueous solution in the step of electrolytically contacting is maintained at a temperature of 70 °C.

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6. The process of claim 1 wherein the aqueous solution in the step of electrolytically contacting contains 0.4 to 0.5 weight percent TMAH.
7. The process of claim 1 further comprising the step, prior to the step of electrolytically contacting, of nonelectrolytically contacting the workpiece with an aqueous solution containing 0.2 to 2 weight percent TMAH.
8. The process of claim 7 wherein the step of nonelectrolytically contacting comprises spraying the workpiece with the aqueous solution.
9. The process of claim 7 wherein the step of nonelectrolytically contacting comprises immersing the workpiece in the aqueous solution.
10. The process of claim 7 wherein the aqueous solution in the step of nonelectrolytically contacting is maintained at a temperature of 25 to 80 °C.

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11. The process of claim 7 wherein the aqueous solution in the step of nonelectrolytically contacting is maintained at a temperature of 70 °C.
12. The process of claim 1 wherein the workpiece is a screening mask.
13. The process of claim 1 wherein the paste comprises solder.
14. The process of claim 1 wherein the paste comprises at least one metal selected from the group consisting of molybdenum, copper, tungsten, nickel, gold, palladium, platinum and silver.
15. The process of claim 1 wherein the paste residue comprises an inorganic material selected from the group consisting of ceramic and glass.
16. The process of claim 1 wherein the paste comprises a polymeric binder.